

## **Lead Free Soldering Summit**

July 13 – July 14, 2005

American Competitiveness Institute  
Philadelphia, Pennsylvania

The American Competitiveness Institute (ACI) held a Lead Free Soldering Summit on July 13 and July 14 at its facilities in Philadelphia, Pennsylvania. The summit concentrated on the unique requirements of the military and aerospace electronics community. Representatives of all three services (Army, Navy, Air Force), NASA, government, industry, and academia were in attendance, providing technical and programmatic Lead Free Soldering presentations.

While the WEEE and RoHS Directives stipulate that military and aerospace electronics are exempt, due to the relative small size of the military and aerospace electronics – less than 1% - it is inevitable that when the commercial electronics markets convert their product lines to Lead Free Solders the military and aerospace electronics will be forced to comply.

Lead Free Soldering impacts not only electronics production, but will also affect hardware reliability, rework and repair, program sustainment, configuration management, the supply chain, and the introduction of Commercial-Off-The Shelf (COTS) as a result of Defense Acquisition Reform. The summit's goals were:

- Identify the Lead Free Soldering activities and plans supporting the military and aerospace electronics community – What Do We Know?
- Identify areas of concern for the transition to Lead Free – What Do We Need To Know?
- Establish a strategy on how to implement Lead Free Soldering in the military and aerospace electronics community – How Do We Get There?

As an output of summit, technical and programmatic challenges were identified that are specific to the military and aerospace electronics community. Action plans to perform applied research and development to resolve the identified issues were discussed. Participants agreed that a follow-up summit to update the state of the art in Lead Free Soldering for high reliability military and aerospace electronics applications should be held.



Participants at the July 13 – July 14 Lead Free Soldering Summit